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**Optične aktivne komponente in naprave - Preskusni in merilni postopki - 6. del:  
Univerzalne medetažne plošče za preizkušanje in merjenje fotoniskih naprav (IEC  
62150-6:2022)**

Fibre optic active components and devices - Test and measurement procedures - Part 6:  
Universal mezzanine boards for test and measurement of photonic devices (IEC 62150-  
6:2022)

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Aktive Lichtwellenleiter-Bauteile und Bauelemente - Prüf- und Messverfahren - Teil 6:  
Universelle Mezzanine Platinen zur Prüfung und Messung von photonischen  
Baugruppen (IEC 62150-6:2022)

Composants et dispositifs actifs fibroniques - Procédures d'essais de base et de  
mesures - Partie 6: Cartes mezzanines universelles pour les essais et les mesures des  
dispositifs photoniques (IEC 62150-6:2022)

**Ta slovenski standard je istoveten z: EN IEC 62150-6:2022**

**ICS:**

33.180.20	Povezovalne naprave za optična vlakna	Fibre optic interconnecting devices
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EUROPEAN STANDARD

EN IEC 62150-6

NORME EUROPÉENNE

EUROPÄISCHE NORM

March 2022

ICS 33.180.20

English Version

Fibre optic active components and devices - Test and  
measurement procedures - Part 6: Universal mezzanine boards  
for test and measurement of photonic devices  
(IEC 62150-6:2022)

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und Messverfahren - Teil 6: Universelle Mezzanine Platinen  
zur Prüfung und Messung von photonischen Baugruppen  
(IEC 62150-6:2022)

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**EN IEC 62150-6:2022 (E)****European foreword**

The text of document 86C/1721/CDV, future edition 1 of IEC 62150-6, prepared by SC 86C "Fibre optic systems and active devices" of IEC/TC 86 "Fibre optics" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62150-6:2022.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022-12-04
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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050-731	-	International Electrotechnical Vocabulary - Part 731: Optical fibre communication	-	-
IEC 62150-1	-	Fibre optic active components and devices - Test and measurement procedures - Part 1: General and guidance	EN 62150-1	-
IEC TR 63072-1	-	Photonic integrated circuits - Part 1: Introduction and roadmap for standardization	-	-

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IEC 62150-6

Edition 1.0 2022-01

# INTERNATIONAL STANDARD



**Fibre optic active components and devices – Test and measurement procedures –  
Part 6: Universal mezzanine boards for test and measurement of photonic devices**

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INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

ICS 33.180.20

ISBN 978-2-8322-1074-9

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**FIBRE OPTIC ACTIVE COMPONENTS AND DEVICES –  
TEST AND MEASUREMENT PROCEDURES –****Part 6: Universal mezzanine boards for test and  
measurement of photonic devices**

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The text of this International Standard is based on the following documents:

Draft	Report on voting
86C/1721/CDV	86C/1752/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

A list of all parts in the IEC 62150 series, published under the general title *Fibre optic active components and devices – Test and measurement procedures*, can be found on the IEC website.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/publications](http://www.iec.ch/publications).

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## INTRODUCTION

This document defines a generic electro-optic mezzanine board for the test and measurement of micro-optical and micro-photonic devices, including a wide diversity of photonic integrated circuit (PIC) technologies including, but not limited to, transceivers, switches, sensors, neuromorphic networks, LiDAR and quantum integrated circuits. The board size and shape would allow two mezzanine boards to be mounted, side-by-side, on a larger Eurocard form factor daughtercard, which itself can be docked into and powered from a backplane system. Alternatively, each mezzanine board can be operated alone, for example on a lab bench powered from a bench supply.

The purpose of this generic mezzanine board concept is to allow like-for-like comparative characterisation of devices under test (DUTs) with respect to one another and to measure the performance of DUTs within larger test environments, relevant to their targeted application, such as data centre systems, high performance computers, automotive or 5G cabinets. The mezzanine board PCB will be designed to accommodate very high-speed electronic signals and a high-speed electronic signal interface to allow external test equipment such as test pattern generators, bit error rate testers and communication signal analysers to drive the device under test (DUT).

This approach will be instrumental in accelerating commercial adoption of micro-photonic devices as they will provide a common benchmark, against which to evaluate the true performance of a DUT. For example, power consumption is an increasingly important figure of merit for optical micro-transceivers in ICT systems; however, the declared values of power consumption as interpreted by the developer often do not reflect the true power consumption of a device under test in operation. The mezzanine board will therefore include provision for a smaller detachable power distribution and sensor mezzanine board allowing multiple tuneable voltages to be provided to the device under test and real-time current or power measurement for each voltage.

Variants of these mezzanine boards have been successfully developed and adopted within the European research and development projects European FP7 project PhoxTrot [1]<sup>1</sup>, European H2020 Nephelē [2] and European H2020 COSMICC [3]. Annex A provides an introduction to these projects.

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<sup>1</sup> Numbers in square brackets refer to the Bibliography.